HB30 Heavy Wire Bonder
Motorized Z- & Y- Axes

+ 100µ to 500µ Aluminium Wire
+ 6,5” TFT Touch Screen
+ 100 Program Storage Capacities
+ Built in Dual Fiber Optic illuminator
+ Motorised Z Bond Head
+ Motorized Y travel for Step-Back loop control
+ 3:1 ratio X-Y manipulator
+ Loop Profile Programmable
+ Stitch bonding
+ Ribbon bonding
+ Semi-auto, Step and Manual Bonding Mode
HB30 Heavy Wire Bonder

The HB30 is a **Bench Top Size Wire Bonder**, ideal for laboratories, pilot and pre-production runs and small scale production lines. Easy operation with **TFT Touch Screen** Operator System. Direct access and simple adjustment to all bond parameters and programs.

**Technical Specifications**

<table>
<thead>
<tr>
<th>Specification</th>
<th>Details</th>
</tr>
</thead>
<tbody>
<tr>
<td>Ultrasonic system</td>
<td>PLL US System</td>
</tr>
<tr>
<td>Ultrasonic power</td>
<td>50 Watt Output</td>
</tr>
<tr>
<td>Bond time</td>
<td>0 - 10 sec.</td>
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<tr>
<td>Bond force</td>
<td>50 - 1800 cN</td>
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<tr>
<td>Aluminium wire diameter</td>
<td>100 to 500 µm</td>
</tr>
<tr>
<td>Ribbon size max.</td>
<td>300 x 1500 µm (Option 300 x 2000 µm)</td>
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<tr>
<td>Wire termination</td>
<td>Front Cut</td>
</tr>
<tr>
<td>Wire feed angle</td>
<td>90°</td>
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<tr>
<td>Motorized Y travel</td>
<td>Stepback up to 17 mm</td>
</tr>
<tr>
<td>Motorized Z travel</td>
<td>20 mm</td>
</tr>
<tr>
<td>Fine Table motion</td>
<td>15 mm</td>
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<tr>
<td>Mouse ratio</td>
<td>3:1 (Option 6:1)</td>
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**Electrical Requirements**

100 - 240V +/-10% 50/60 Hz 10A max.

**Physical Dimensions**

680 mm [27”] W x 640 mm [25”] D x 490 mm [19”] H

**Weight**

Net 50 kg

**Industry Standards**

CE Standards

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**Accessories:**

- **H50 Spotlight Targeting System**
- **H51 Manual Z-Axis Control**
- **H28 Stage Ø 90mm**
- **H89 Video Targeting System**
- **H52 Dynamic Search**

Made in Germany

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